

Painotekniikoilla älykkyyttä kaikkialle

BioÄly-hanke, seminaari, 10.3.2020

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research.tuni.fi/lfe

Laboratory for Future Electronics

- LFE investigates technologies and solutions related to energy-autonomy (storage and harvesting), sensors, conformable wearable electronics (soft/stretchable, on-skin, textile), and hybrid system integration.
- Strong emphasis is placed on scalable, low-cost manufacturing methods such as **printing** as well as their integration with more conventional component assembly methods.
- LFE explores new device and circuit approaches based on printable organic and metal oxide semiconductors.



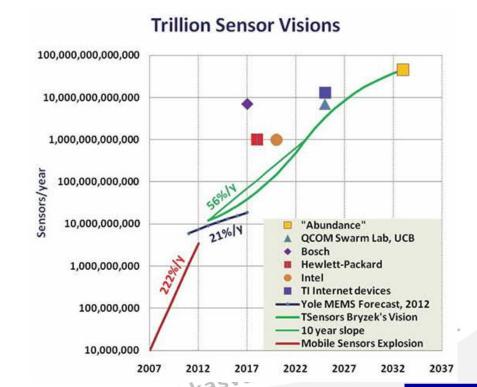
Outline

- Internet-of-Everything
- Printed Electronics
- Stick-it-on-Device
- Research examples
- LFE infrastructure and on-going research



Trillion sensor vision

- Billions (and potentially trillions) of MCUs are needed every year.
- World's annual manufacturing rate of MCUs is around tens of billion pieces.
- Paradigm shift in manufacturing is needed



Source: Thin Film Electronics

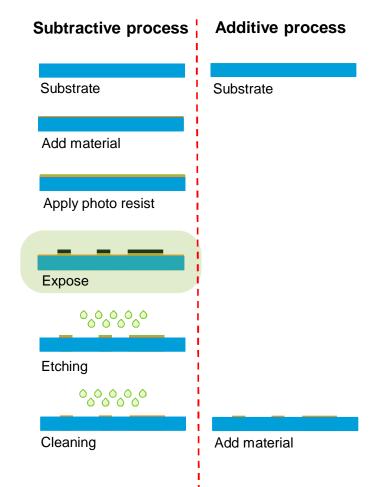
Source: FuturistSpeakers.com

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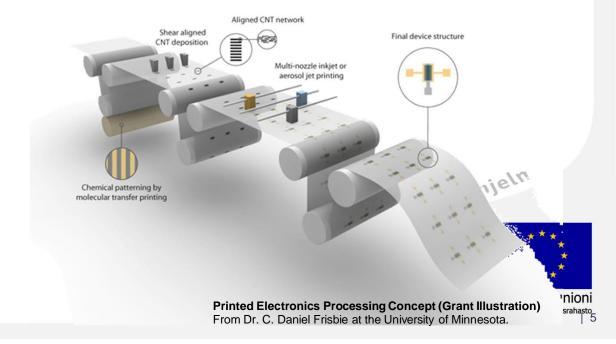
10.3.2020

Printed electronics



"Instead of printing graphic arts inks, families of electrically functional electronic or optical inks are used to print active or passive devices, such as thin film transistors or resistors"

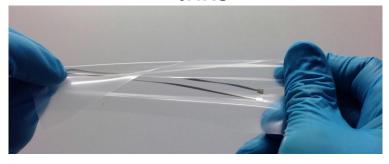
- Additive => less material waste
- No etching => less harsh chemicals
- Less process steps => simplified process



Printed Electronics

TOTAL READS SEC.

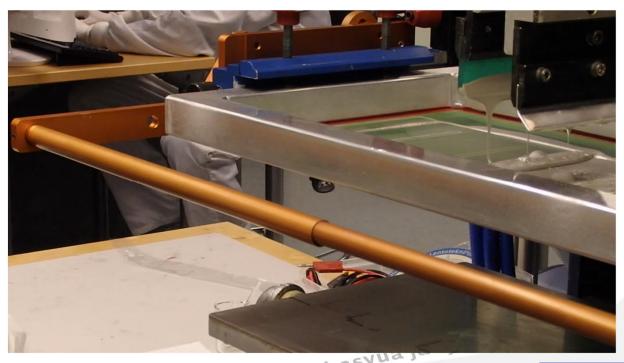
Inks



Thin foils

Main advantages:

- Simplified process
- Large-area
- Cost-effective



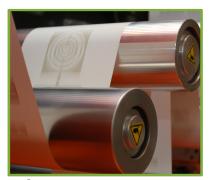
Printing technologies





Large Area Printing & Patterning Techniques

High volume printing processes



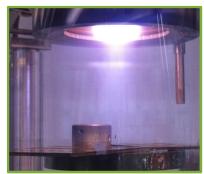
- Gravure
- Flexography
- Offset
- Lithography

Digital patterning processes



- Inkjet printing
- Aerosol jet printing
- Laser transfer & machining
- Micro-plasma printing
- Syringe deposition
- Xerography

Further patterning & deposition processes



- Vapor phase deposition
- Soft & large area lithography
- Nano-imprint lithography
- Pad printing
- Wetting/dewetting
- Hot stamping

Solution coating processes



- Slot-die coating
- Wire bar coating
- Curtain coating

Kestävää kasvua ja työtä -ohjelma





https://nakedapproach.fi/

Stick-it-on-Devices "sticker computer"

Turn "old world" objects to smart devices

The Nordic Digital Promise: Four Theses on a Hyperconnected Society



Mass manufacturable

 billions of components and devices will be needed in the future (i.e. "trillion sensor visions")

• produced via low cost manufacturing processes

Form factor

easy embedding into old world objects

concepts like "sticker computing"

Self-powering

all units will operate on the basis of harvested energy

Either shared or self gathered from renewable source

Connectivity

Function

 new connectivity technologies are needed to reach the peripheral "zero-resource" devices

 each device should increase the "functional potential" of the environment – e.g. utilizing: sensing, actuating, computing, or connecting functions.

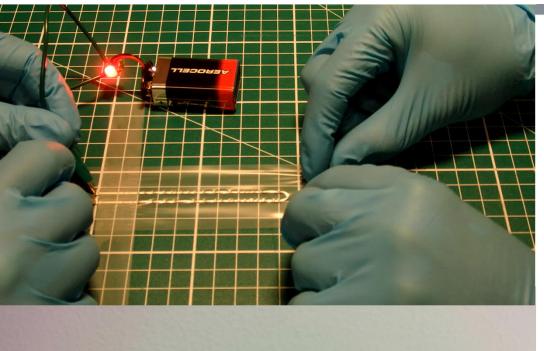
On the Road to Digital Paradise











Example: Form factor

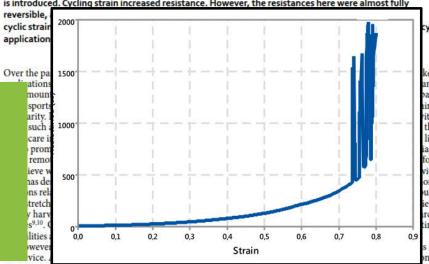
SCIENTIFIC REPORTS

Received: 21 December 2015 Accepted: 22 April 2016 Published: 13 May 2016

OPEN Screen-Printing Fabrication and Characterization of Stretchable **Electronics**

Jari Suikkola, Toni Björninen, Mahmoud Mosallaei, Timo Kankkunen, Pekka Iso-Ketola, Leena Ukkonen, Jukka Vanhala & Matti Mäntysalo

This article focuses on the fabrication and characterization of stretchable interconnects for wearable electronics applications. Interconnects were screen-printed with a stretchable silver-polymer composite ink on 50-um thick thermoplastic polyurethane. The initial sheet resistances of the manufactured interconnects were an average of 36.2 m Ω/\Box , and half the manufactured samples withstood single strains of up to 74%. The strain proportionality of resistance is discussed, and a regression model is introduced. Cycling strain increased resistance. However, the resistances here were almost fully



Silver flakes: ~36 mΩ/□

Single pull strain: 74%

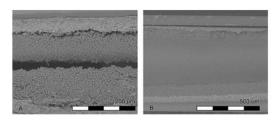
• $R(\epsilon: 10\%) \sim 2 \times R_0$

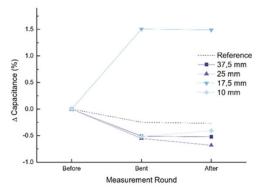
 $R(ε: 20\%) \sim 4 \times R_0$

Up to 1 000 cycles (20%)

Supercapacitors for non-toxic energy storage

Non-toxic gelatin electrolyte



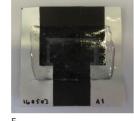


A. Railanmaa et al., Appl. Phys. A, in press

Monolithic supercaps









J. Keskinen et al., J. Energy Storage 16, 243 (2018)

- Non-toxic materials: graphite, activated carbon, chitosan, paper, water, table salt
- Bill of materials few cents/device
- Fabrication by screen or stencil printing, bar coating
- Can hold energy for up to a month with barrier film

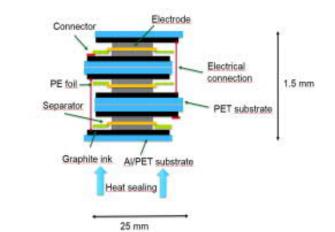






Example: Self-powering

- Joint demonstrator with Confidex
- Commercial wireless temperature tracker was modified to replace coin cell with OPV module and printed supercap module
- OPV and supercaps fit within NFC read antenna and did not significantly affect reading
- Indoor light sufficient to power device and charge supercap, and supercap can power device for 18 hours in dark
- Best Poster award at InnoLAE2019 conference







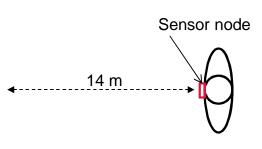


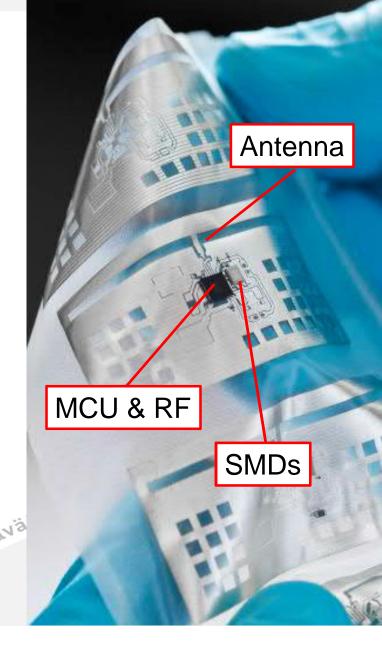




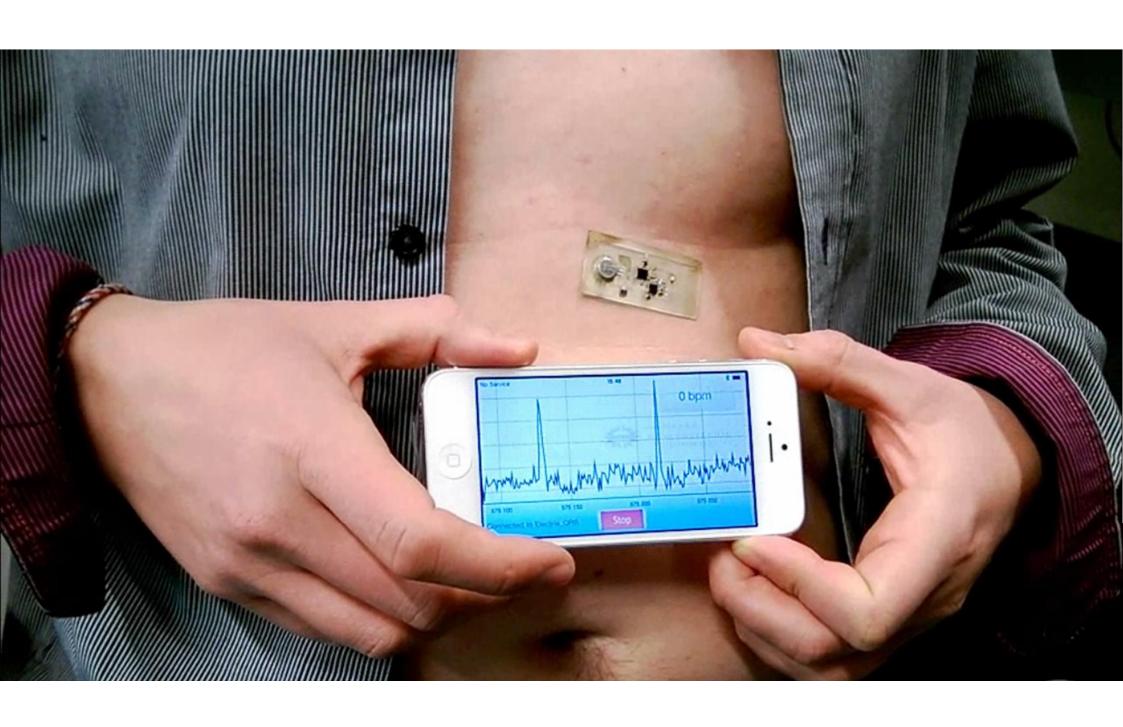
Example: Connectivity

- Band-aid like sensor attached directly on the body
 - 14 m reading distance (P_{TX} @ 0 dBm)
- Commercial NRF51822 (SoC) from Nordic Semi (WLCSP package)
 - Bluetooth low-energy
 - A/D converters
- In addition, there are the
 - Antenna (printed),
 - Amplifier and discrete components
 - Gel-electrodes for measuring the ECG signal.





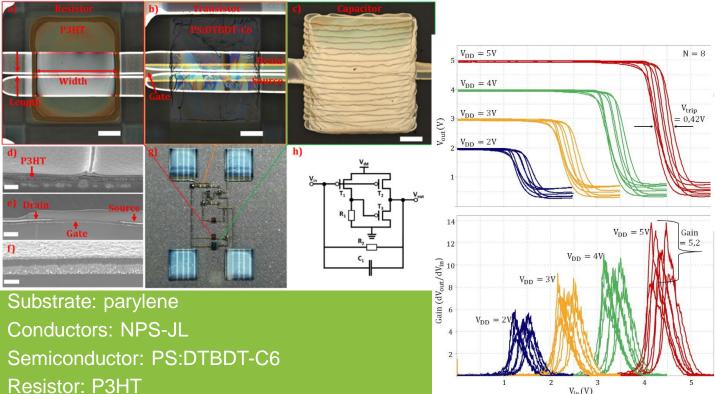
Sillanpää, et al.,, ESTC, 2014

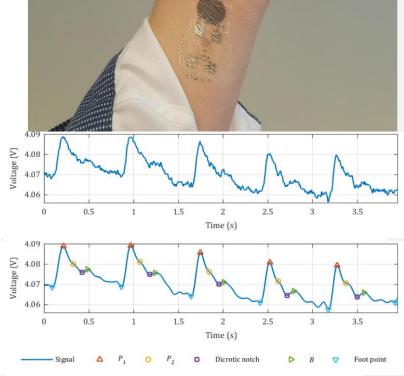


Laurila, et al., J-EDS, DOI: 10.1109/JEDS.2019.2915028

Example: Thin film circuitry

Collaboration between Tampere University, Tampere University Hospital and Yamagata University (Prof. Tokito)

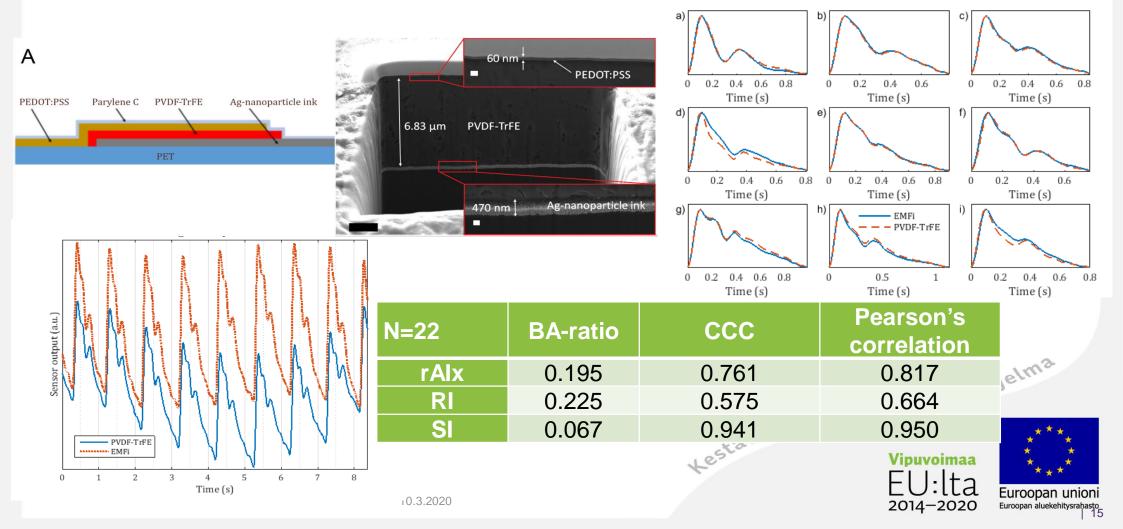


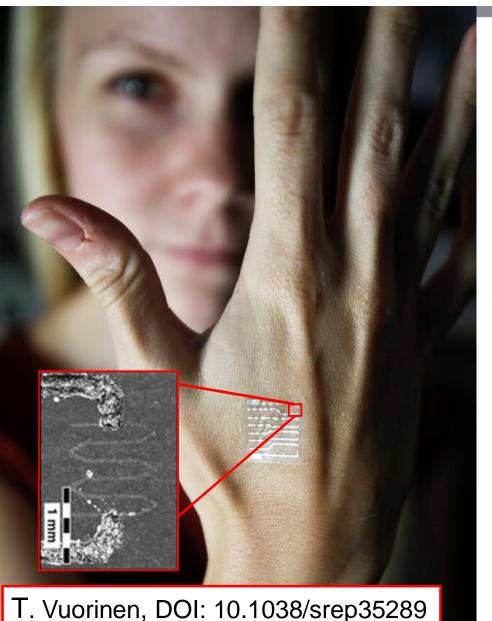


PARAMETER	A VERAGE	STD.
(N=25)		DEV
RI, SENSOR	0.388	0.031
RI, OUTPUT	0.404	0.044
RAIX, SENSOR	0.615	0.045
R AI X, OUTPUT	0.626	0.057

M.-M. Laurila, et al., DOI: 10.1109/JSEN.2019.2934943

Example: Pressure sensor





Example: Temperature sensor

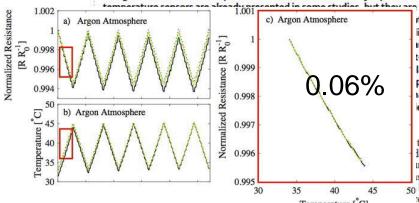


Received: 15 April 2016 Accepted: 26 September 2016 Published: 18 October 2016

OPEN Inkjet-Printed Graphene/ **PEDOT:PSS Temperature** Sensors on a Skin-Conformable Polyurethane Substrate

Tiina Vuorinen, Juha Niittynen, Timo Kankkunen, Thomas M. Kraft & Matti Mäntysalo

Epidermal electronic systems (EESs) are skin-like electronic systems, which can be used to measure several physiological parameters from the skin. This paper presents materials and a simple, straightforward fabrication process for skin-conformable inkjet-printed temperature sensors. Epidermal



mainly fabricated using rtes have several processing izing printing processes, the inufacturing costs and reducing t-printed graphene/PEDOT:PSS laster (adhesive bandage). phere and the graphene/ ian 0.06% per degree Celsius ependence.

to a more mobile monitoring with weight, and the monitoring elecrement devices. Low levels of elecstantly radiating heat through the 50 be measured using skin mounted reason a skin thermometer can be

Temperature [°C] reason a skin thermometer can be utilized in the investigation of cardiovascular nearth, physical activity and ulcer prediction and prevention¹⁻⁴. A variety of body monitoring systems are already familiar in both the hospital environment and more casual environments for tracking physical activity. To improve the skin/sensor interface and wearability (comfort and ease of application) in these tracking situations, the development is transitioning from rigid and planar electronic systems towards more adaptable, skin-like electronics 5.6. These types of soft, stretchable, thin-film devices are

LFE infrastucture

Contact: Dr. Jari Keskinen, Staff Scientist jari.keskinen@tuni.fi
research.tuni.fi/lfe

250 m2 Lab space 60 m2 Clean-room PrintLab Thin-film fabrication



Inkjet (with NIR and UV post processing), Modular printing system (gravure/flexo/rotary screen/wet and dry lamination / online annealing), screen printer, high-resolution inkjet



Inert glovebox-system including evaporator (thermal, e-beam), probe station, spin-coating, vacuum hot-plate, inkjet, ALD



LFE On-going projects

Academy of Finland

- HiFlex (Academy of Finland, 2017-2021) high speed solution processed circuitry for wireless communication, based on tunnel diodes and transistors
- LightningSense (Academy of Finland, 2018-2021, with TAU
 Chemistry and Aalto Microelectronics) energy autonomous
 wireless sensor node with printed light harvesters (lead-free
 perovskites) and energy storage (supercapacitors)
- VBA (AoF, 2017-2021) Vascular Biomechanics Assessment using printed soft electronics and advanced signal processing
- PII (AoF-FIRI, 2019-2021), Printed Intelligence Infrastructure
- EpiPrint (AoF Research fellow) Development of epidermal electronics using nano-materials and advanced printing technologies 9/2015-8/2020

Business Finland:

- Elastronics (BF co-innovation, 9/2018-8/2020) printed stretchable hybrid electronics for wearables
- ECOtronics (BF co-innovation, 10/2019-9/2021) sustainable electronics and optics

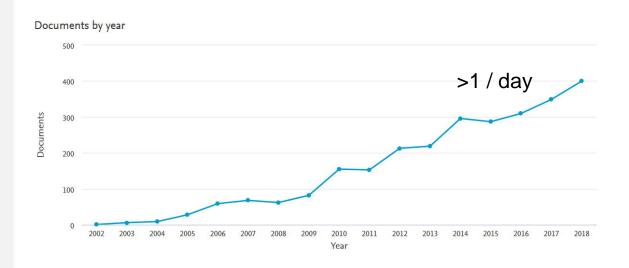
European Union

- Smart2Go (EU H2020, 2019 2021, coordinator Fraunhofer) – smart and flexible energy supply platform for wearable electronics
- Charisma (EU Marie Curie ITN, 2019 2022) engineering chemical irreversibility to prototype responsive smart labels
- BioÄly (EAKR EU-regional funding, 2018-2020), sustainable biodegradable materials
- InCOmESS (EU H2020, 2020-2023) INnovative polymer-based COmposite systeMs for high-efficient Energy Scavenging and Storage



Scopus analysis 4.11.2019 "Printed electronics" in ABS-KEY-TITLE

"Printed electronics" research articles



>1 article per day (400/year) Approx 2700 articles from 2002 Finland is top 7 Tampere in top 2

